

## REMARKS

In response to the above-identified Office Action, Applicants amend the application and seek reconsideration thereof. In this response, Applicants amend claim 20. No claims have been cancelled and no new claims have been added. Accordingly, 4-6, 9-11, 14-16 and 19-21 are pending.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attachment is captioned "Version With Markings To Show Changes Made."

### **I. Objections**

The Examiner objects to claim 20 for including an informality. Claim 20 has been amended to change the phrase "The integrated circuit" to "The multilayer structure" as suggested by the Examiner. Accordingly, reconsideration and withdrawal of the objection to Claim 20 are requested.

### **IV. Claims Rejected Under 35 U.S.C. §103(a)**

Claims 4, 5, 9, 10, 14 and 15 stand rejected under 35 U.S.C. § 103(a) as being obvious over U.S. Patent No. 5,665,643 issued to Shin (hereinafter "Shin") in view of U.S. Patent No. 6,277,730 issued to Yuasa, et al. (hereinafter "Yuasa") and U.S. Patent No. 5,747,361 issued to Ouellet (hereinafter "Ouellet"). Applicants respectfully disagree for the following reasons. The Examiner relies upon Yuasa to disclose "an interconnection comprising an aluminum alloy layer 12b that contains 0.5 atomic percent of copper" and further states that it would have been obvious to form an outer layer of Shin using 0.5 atomic percent of copper to prevent electromigration. Yuasa was filed on February 16, 1999 and issued as a patent on August 21, 2001. The Applicants assert that Yuasa may not be used as a reference to reject the claims under

35 U.S.C. § 103 because Applicants hereby make a Declaration under 37 C.F.R. § 1.131 showing a completion of the invention in this country before the filing date of Yuasa. Further, Applicants' filing date of March 19, 1999 is less than one year from Yuasa's filing date of February 16, 1999. The Applicants submit the Declarations pursuant to § 1.131 herewith. For this reason, Yuasa cannot be used as a reference against Applicants' claims. The remaining references Shin and Ouellet do not teach or suggest an interconnection comprising an aluminum copper titanium alloy layer that contains 0.5 atomic percent of copper. Thus, each of the elements of independent claims form 9, 14 and 16 are not taught by Shin in view of Ouellet. Therefore, these claims are not obvious over the cited references. Accordingly, reconsideration and withdrawal of the obviousness rejection of claims 4, 9 and 14 are requested.

In regard to claims 5, 10 and 15, these claims depend from independent claims 4, 9 and 14, respectively, and incorporates the limitations thereof. Therefore, at least for the reasons mentioned in regard to claims 4, 9 and 14, these claims are not obvious over Shin in view of Ouellet. Accordingly, reconsideration and withdrawal of the obviousness rejections of claims 5, 10 and 15 are requested.

Claims 6, 11, 16 and 19-21 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Shin in view of Yuasa, Ouellet and further in view of U.S. Patent No. 5,635,763 issued to Inoue, et al. (hereinafter "Inoue"). Applicants disagree for the following reasons.

Yuasa cannot be used as a reference against the Applicants' claims for the reasons mentioned above. Further, Inoue does not teach an aluminum copper titanium alloy having 0.5 atomic percent copper and thus does not cure the defects of Shin and Ouellet. Thus, the cited references do not teach each of the elements of independent claim 16 or claims 6 and 11 which

depend from independent claims 4 and 9 for the reasons mentioned above. Accordingly, reconsideration and withdrawal of the obviousness rejection of claims 6, 11 and 16 are requested.

In regard to claims 19-21, these claims depend from independent claim 16 and incorporate the limitations thereof. Thus, at least for the reasons mentioned in regard to claim 16, these claims are not obvious over Shin in view of Ouellet and Inoue. Accordingly, reconsideration and withdrawal of the obviousness rejections of claims 19-21 are requested.


### **CONCLUSION**

In view of the foregoing, it is believed that all claims now pending, namely claims 4-6, 9-11, 14-16 and 19-21 patentably define the subject invention over the prior art of record, and are in condition for allowance and such action is earnestly solicited at the earliest possible date. If the Examiner believes that a telephone conference would be useful in moving the application forward to allowance, the Examiner is encouraged to contact the undersigned at (310) 207 3800.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

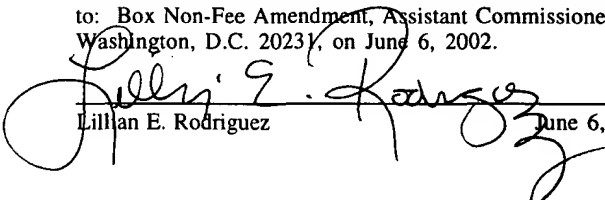
Dated: June 6, 2002

  
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### **CERTIFICATE OF MAILING:**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box Non-Fee Amendment, Assistant Commissioner for Patents, Washington, D.C. 20231, on June 6, 2002.

  
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Lillian E. Rodriguez June 6, 2002

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**IN THE CLAIMS**

Please amend the claims as follows:

20. (Amended) The [integrated circuit] multilayered structure of claim 16, wherein the aluminum-copper-titanium alloy layer comprises about 0.5 atomic percent copper and about 0.1 atomic percent titanium